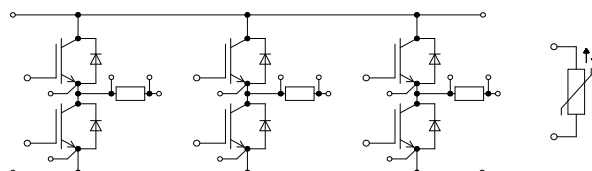
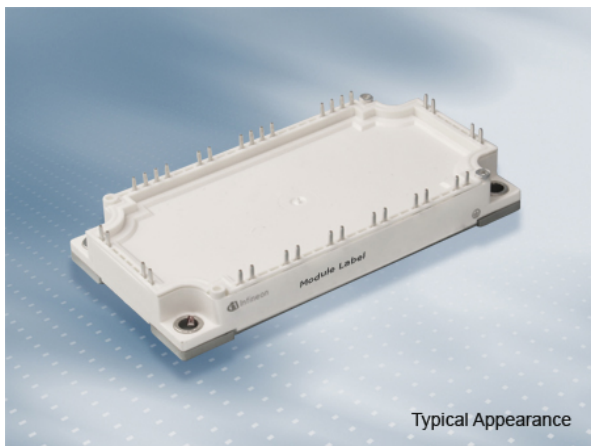


MIPAQ™base Modul mit Trench/Feldstopp IGBT4 und Emitter Controlled HE Diode und Strommesswiderstand

MIPAQ™base module with Trench/Fieldstop IGBT4 and Emitter Controlled HE diode and current sense shunt

Vorläufige Daten / Preliminary Data



$V_{CES} = 1200V$
 $I_{C\ nom} = 100A / I_{CRM} = 200A$

Typische Anwendungen

- Motorantriebe
- Servoumrichter

Typical Applications

- Motor Drives
- Servo Drives

Elektrische Eigenschaften

- Niedrige Schaltverluste
- $T_{vj\ op} = 150^{\circ}C$
- Niedriges V_{CEsat}

Electrical Features

- Low Switching Losses
- $T_{vj\ op} = 150^{\circ}C$
- LOW V_{CEsat}

Mechanische Eigenschaften

- Hohe Last- und thermische Wechselfestigkeit
- Isolierte Bodenplatte
- Kupferbodenplatte
- Standardgehäuse

Mechanical Features

- High Power and Thermal Cycling Capability
- Isolated Base Plate
- Copper Base Plate
- Standard Housing

Module Label Code

Barcode Code 128



DMX - Code



Content of the Code

Content of the Code	Digit
Module Serial Number	1 - 5
Module Material Number	6 - 11
Production Order Number	12 - 19
Datecode (Production Year)	20 - 21
Datecode (Production Week)	22 - 23

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Vorläufige Daten
Preliminary Data

IGBT, Wechselrichter / IGBT, Inverter
Höchstzulässige Werte / Maximum Rated Values

Kollektor-Emitter-Sperrspannung Collector-emitter voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{CES}	1200	V
Kollektor-Dauergleichstrom Continuous DC collector current	$T_C = 95^{\circ}\text{C}, T_{vj} = 175^{\circ}\text{C}$	$I_{C\text{ nom}}$	100	A
Periodischer Kollektor-Spitzenstrom Repetitive peak collector current	$t_P = 1\text{ ms}$	I_{CRM}	200	A
Gesamt-Verlustleistung Total power dissipation	$T_C = 25^{\circ}\text{C}, T_{vj} = 175^{\circ}\text{C}$	P_{tot}	515	W
Gate-Emitter-Spitzenspannung Gate-emitter peak voltage		V_{GES}	+/-20	V

Charakteristische Werte / Characteristic Values

			min.	typ.	max.		
Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage	$I_C = 100\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 100\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 100\text{ A}, V_{GE} = 15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_{CE\text{ sat}}$	1,75 2,00 2,05	2,10	V V V	
Gate-Schwellenspannung Gate threshold voltage	$I_C = 4,00\text{ mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$		V_{GEth}	5,2	5,8	6,4	V
Gateladung Gate charge	$V_{GE} = -15\text{ V} \dots +15\text{ V}$		Q_G	0,80			μC
Interner Gatewiderstand Internal gate resistor	$T_{vj} = 25^{\circ}\text{C}$		R_{Gint}	7,5			Ω
Eingangskapazität Input capacitance	$f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		C_{ies}	6,30			nF
Rückwirkungskapazität Reverse transfer capacitance	$f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		C_{res}	0,27			nF
Kollektor-Emitter-Reststrom Collector-emitter cut-off current	$V_{CE} = 1200\text{ V}, V_{GE} = 0\text{ V}, T_{vj} = 25^{\circ}\text{C}$		I_{CES}			1,0	mA
Gate-Emitter-Reststrom Gate-emitter leakage current	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}, T_{vj} = 25^{\circ}\text{C}$		I_{GES}			100	nA
Einschaltverzögerungszeit, induktive Last Turn-on delay time, inductive load	$I_C = 100\text{ A}, V_{CE} = 600\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 1,6\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_{don}	0,16 0,17 0,18			μs μs μs
Anstiegszeit, induktive Last Rise time, inductive load	$I_C = 100\text{ A}, V_{CE} = 600\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 1,6\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_r	0,025 0,03 0,03			μs μs μs
Abschaltverzögerungszeit, induktive Last Turn-off delay time, inductive load	$I_C = 100\text{ A}, V_{CE} = 600\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 1,6\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_{doff}	0,37 0,45 0,48			μs μs μs
Fallzeit, induktive Last Fall time, inductive load	$I_C = 100\text{ A}, V_{CE} = 600\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 1,6\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_f	0,06 0,11 0,13			μs μs μs
Einschaltverlustenergie pro Puls Turn-on energy loss per pulse	$I_C = 100\text{ A}, V_{CE} = 600\text{ V}, L_S = 40\text{ nH}$ $V_{GE} = \pm 15\text{ V}, di/dt = 3700\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $R_{Gon} = 1,6\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{on}	4,00 6,50 7,50			mJ mJ mJ
Abschaltverlustenergie pro Puls Turn-off energy loss per pulse	$I_C = 100\text{ A}, V_{CE} = 600\text{ V}, L_S = 40\text{ nH}$ $V_{GE} = \pm 15\text{ V}, du/dt = 3400\text{ V}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $R_{Goff} = 1,6\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{off}	7,60 11,0 12,5			mJ mJ mJ
Kurzschlussverhalten SC data	$V_{GE} \leq 15\text{ V}, V_{CC} = 800\text{ V}$ $V_{CEmax} = V_{CES} - L_{SCE} \cdot di/dt$ $t_P \leq 10\ \mu\text{s}, T_{vj} = 150^{\circ}\text{C}$		I_{SC}	400			A
Wärmewiderstand, Chip bis Gehäuse Thermal resistance, junction to case	pro IGBT / per IGBT		R_{thJC}			0,29	K/W
Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink	pro IGBT / per IGBT $\lambda_{Paste} = 1\text{ W}/(\text{m}\cdot\text{K})$ / $\lambda_{grease} = 1\text{ W}/(\text{m}\cdot\text{K})$		R_{thCH}	0,086			K/W

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